

# MATERIAL DECLARATION



NO	BREAKDOWN OF PART	MANUFACTURER	MATERIAL NAME	CHEMICAL SYMBOL	CAS NO.	%	TOTAL		2.0500	
							WEIGHT	SUBSTANCE MASS. (Mg)	%	SUBSTANCE %
1	Alumina Substrate	Leatec Fine Ceramics	Al2O3 substrate	Al2O3	1344-28-1	96.00	88.00	84.480	4.293	4.1210
				SiO2	14808-60-7	3.00		2.640		0.1288
				MgO	1309-48-4	1.00		0.880		0.0429
2	Resistor Layer	SUMITOMO	Resistive	Silver	744-22-4	30.00	60.00	18.000	2.927	0.8780
				Paste	744-05-3	10.00		6.000		0.2927
				Puthenium Oxide	12036-10-1	10.00		6.000		0.2927
				Lead Oxide	1317-36-8	15.00		9.000		0.4390
				Boron Trioxide	1303-86-2	2.00		1.200		0.0585
				Aluminium Oxide	1344-28-1	2.00		1.200		0.0585
				Silicon Dioxide	7631-86-9	10.00		6.000		0.2927
				Zinc Oxide	1314-13-2	2.00		1.200		0.0585
				Copper Oxide	1317-38-0	0.50		0.300		0.0146
				Manganese Oxide	1317-35-7	1.50		0.900		0.0439
				Tantalum Oxide	1314-61-0	1.50		0.900		0.0439
				Titanium Dioxide	13463-67-7	0.50		0.300		0.0146
Terpineol	8000-41-7	10.00	6.000	0.2927						
Dibutyl Decanedioate	109-43-3	5.00	3.000	0.1463						
3	Flange	HCT	Lead Frame	Cu	7440-50-8	100.00	122.00	122.000	5.951	5.9512
4	Solder	SHENMAO	Lead-free solder	Sn	7440-31-5	94.30	135.00	127.305	6.585	6.2100
				Ag	7440-22-4	3.00		4.050		0.1976
				Cu	7440-50-8	0.50		0.675		0.0329
				Rosin	8050-09-7	2.00		2.700		0.1317
				Activator	Not Established	0.10		0.135		0.0066
				Others	Not Established	0.10		0.135		0.0066
5	Molding	ETERNAL	Epoxy Resin	Crystalline Silica	14808-60-7	72.50	1645.00	1192.625	80.244	58.1768
				Fused Silica	60676-86-0	10.00		164.500		8.0244
				Epoxy Resin	29690-82-2	10.00		164.500		8.0244
				Phenol Resin	9003-35-4	5.00		82.250		4.0122
				Metal hydroxide	-	2.00		32.900		1.6049
				Carbon Black	1333-86-4	0.50		8.225		0.4012

